

Summary

The purpose of this notification is to advise customers of top marking changes for Xilinx[®] 7 series, Zynq[®]-7000, Zynq[®] UltraScale+[™], UltraScale[™], and UltraScale+[™] commercial / industrial “XC”, Defense “XQ”, and Automotive-grade “XA” devices.

In continuation of our 2D barcode top marking, Xilinx will be simplifying further the topside marking for all Xilinx 7 series, Zynq-7000, Zynq UltraScale+, UltraScale, and UltraScale+ commercial / industrial “XC”, Defense “XQ”, and Automotive-grade “XA” devices (Refer to [XCN16014](#) & [XCN18016](#)). All topside marking will be removed except for Xilinx logo, 2D barcode, and country of origin where family branding is optional. This will allow much improved device-level traceability and security.

The 2D barcode contains a unique serial number that must be scanned using a camera-based application to determine the serial number. The device and package information that were previously found on the top marking can only be retrieved using the unique serial number through an internet-based application either on a mobile device or through a web browser using a portal. Scanning the existing License Plate Number (LPN) provided on the inner box and bag label will allow access to all device information.

FAQs

Q: What’s happening?

Xilinx is making further topside marking simplification (Refer to XCN16014 & XCN18016) with the following change: All topside marking will be removed except for Xilinx logo, 2D barcode, and country of origin where family branding is optional to all Xilinx 7 series, Zynq-7000, Zynq UltraScale+, UltraScale, and UltraScale+ commercial / industrial “XC”, Defense “XQ”, and Automotive-grade “XA” devices.

Q: What is 2D barcode marking?

2D barcode marking is a serialized identifier unique to each die marked on the top side of the device. This marking can be read using industry standard scanners (which are direct part marking capable) to retrieve device information & processing details from either a web application on Xilinx.com or a mobile application (Refer to [XCN16014](#) & [XCN18016](#)).

Q: Why is Xilinx making these changes?

Xilinx is making this change to improve device-level traceability, delivery support, and supply chain safety (Refer to [XCN16014](#) & [XCN18016](#)).

Q: Which products are affected?

This change affects all package, speed, and temperature grade variations for all Xilinx 7 series, Zynq-7000, Zynq UltraScale+, UltraScale, and UltraScale+ commercial / industrial “XC”, Defense “XQ”, and Automotive-grade “XA” devices, including SCD products.

- a. New products, or extended family release on and after July 1, 2019 will only ship with the new simplified top marking.
- b. Existing production devices will transit into new simplified top marking in 2020 or later.

Table 1: Simplifying Top Mark for New Products, or Extended Family Release

Product Line	Device	Anticipated Shipments
XC, XA, XQ	7 Series, Zynq-7000, UltraScale, Zynq UltraScale+, and UltraScale+	July 2019

Table 2a: Simplifying Top Mark for Existing 7 Series, Zynq-7000, and UltraScale Production Products

Product Line	Device (Existing)	Anticipated Shipments
XC, XA, XQ	7 Series, Zynq-7000, and UltraScale	2020 or later

Table 2b: Simplifying Top Mark for Existing XC Zynq UltraScale+ and UltraScale+ Production Products

Device	Estimated Cross Shipping	Device	Estimated Cross Shipping
XCVU9P	To be Defined	XCZU2CG	To be Defined
XCKU3P	To be Defined	XCZU2EG	To be Defined
XCKU5P	To be Defined	XCZU3CG	To be Defined
XCKU9P	To be Defined	XCZU3EG	To be Defined
XCKU11P	To be Defined	XCZU4CG	To be Defined
XCKU13P	To be Defined	XCZU4EG	To be Defined
XCKU15P	To be Defined	XCZU4EV	To be Defined
XCVU3P	To be Defined	XCZU5CG, XCZU5EG, XCZU5EV	To be Defined
XCVU5P	To be Defined	XCZU6CG	To be Defined
XCVU7P	To be Defined	XCZU6EG	To be Defined
XCVU11P	To be Defined	XCZU7CG	To be Defined
XCVU13P	To be Defined	XCZU7EG	To be Defined
XCVU31P	Jul 2020	XCZU7EV	To be Defined
XCVU33P	Jul 2020	XCZU9CG, XCZU9EG	To be Defined
XCVU35P	Jul 2020	XCZU11EG	To be Defined
XCVU37P	To be Defined	XCZU15EG	To be Defined
XCVU45P	Jul 2020	XCZU17EG	To be Defined
XCVU47P	To be Defined	XCZU19EG	To be Defined
		XCZU21DR	To be Defined
		XCZU25DR	To be Defined
		XCZU27DR	To be Defined
		XCZU28DR	To be Defined
		XCZU29DR	To be Defined
		XCZU39DR	To be Defined

Table 2c: Simplifying Top Mark for Existing XA Zynq UltraScale+ Production Products

Device	Estimated Cross Shipping
XAZU2EG	To be Defined
XAZU3EG	To be Defined
XAZU4EV	To be Defined
XAZU5EV	To be Defined

Q: When will this change take effect?

Please refer to [Table 1](#), [Table 2a](#), [Table 2b](#) and [Table 2c](#) for the cross-ship dates.

Q: Does this change impact material qualification?

No, it does not.

Q: What do customers have to do in response to this announcement?

No response is required.

Q: Are manufacturing changes required?

There should not be any impact due to this XCN19014. However, customers are encouraged to review internal inspection and manufacturing practices to ensure the new 2D marking can be fully integrated.

Q: What information is being removed from the standard marking?

Line 1 – Device ID

Line 2 – Package code will no longer be marked.

Q: How can a customer access 2D barcode information?

Refer to [XCN16014](#) & [XCN18016](#) for additional information.

Q: How do I find out more?

Please submit a Service Request via the [Service Portal](#) on www.xilinx.com.

Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
03/25/2019	1.0	Initial release.
12/16/2019	1.1	Added Zynq UltraScale+ and UltraScale+ top mark simplification cross-shipping dates in Tables 2b and 2c .
03/16/2020	1.2	Updated estimated cross-shipment dates.
08/17/2020	1.3	Updated estimated cross-shipment dates from Oct 2020 – Mar 2021 to “To be Defined.”

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